Plaskon SMT-B-1RC

Epoxy; Epoxide

Cookson Electronics - Semiconductor Products

Message:

This material is an epoxy molding compound optimized specifically for PBGA applications. It is a fast cure molding compound for automold applications. It has the same unique resin system as the SMT-B-1, which minimizes warpage and enables trouble-free molding onto rigid and flexible laminate substrates. Minimal dimensional change after molding, post bake and subsequent solder treatment make this compound an excellent choice for PBGA applications.

General Information			
Features	Semi-conductive		
	Good dimensional stability		
	Low warpage		
	Low viscosity		
	Fast curing		
Uses	Application in Automobile Field		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	**Nominal Value**	**Unit**	**Test Method**
Specific Gravity	1.88	g/cm³	ASTM D792
Molding Shrinkage - Flow	0.050	%	ASTM D955
Mechanical	**Nominal Value**	**Unit**	**Test Method**
Flexural Modulus			ASTM D790
22°C	1.28	MPa	ASTM D790
215°C	0.588	MPa	ASTM D790
Flexural Strength			ASTM D790
22°C	0.00971	MPa	ASTM D790
215°C	0.00402	MPa	ASTM D790
Thermal	**Nominal Value**	**Unit**	**Test Method**
Glass Transition Temperature	226	°C	ASTM E1356
CLTE - Flow	1.5E-5	cm/cm/°C	ASTM D696
Thermal Conductivity	0.80	W/m/K	ASTM C177
Electrical	**Nominal Value**	**Unit**	**Test Method**
Volume Resistivity	2.0E+16	ohms·cm	ASTM D257
Dielectric Strength	28	kV/mm	ASTM D149
Dielectric Constant (1 kHz)	3.90		ASTM D150
Dissipation Factor (1 kHz)	4.0E-3		ASTM D150
Flammability	**Nominal Value**	**Unit**	**Test Method**
Flame Rating (3.18 mm)	V-0		UL 94
Oxygen Index	32	%	ASTM D2863

Additional Information

Recommended Storage Temperature: <5°CLife @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 24 monthsLife @ 21°C, defined as not more than 40% loss of spiral flow based on original values.: 5 daysLife @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 2 daysSpiral Flow, 175°C, 1000 psi: 105 cmAutomatic Orifice Viscosity, 175°C: 55 poiseRam Follower Gel Time, 175°C, 1000 psi: 12 secAsh Content: 78 %Hydrolyzable Halides: <1 ppmCull Hot Hardness, Shore D, 75 sec, 175°C: 86Volume Resistivity, 22°C: 2e16 ohm-cmAll test specimens are transfer molded and post cured for 4 hours at 175°C
Linear Thermal Expansion, Alpha 1: 15 cm^-6/cm/°C
Linear Thermal Expansion, Alpha 2: 55 cm^-6/cm/°C

Injection instructions

Resin Transfer Molding:
Preheat Temperature: 85 to 98°C
Molding Temperature: 175°C
Molding Pressure: 800 to 1200 psi
Cycle Time, 175°C: 60 to 150 sec
Post Mold Cure Time, 175°C: 0 to 4 hr

Recommended distributors for this material

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